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Self explanatory.

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Cut and paste these checklists for your use.

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Cut and paste these checklists for your use.

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This part is fairly self evident so there really is no reason to explain it but to say you can learn from failure analysis (FA) but why end up there for lack of DFM/CE.

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This part provides very detailed photo procedures for nearly every process required to assemble your boards. If you did DFM/CE right so will your assembly capability. If not, there's an expensive FA operation, as in Part 2, in your immediate future. After FA, you'll know if it was your design or supplier evaluation and qualification process, or both, at fault.

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**NOTE: PCB FABRICATION PROCEDURES ALSO AVAILABLE ON A CUSTOM BASIS
THOUGH I HAVE MANY OF THESE FOR VARIOUS SHOPS THROUGHOUT THE WORLD.
HOWEVER, THERE ARE SO MANY PROCESSES AND DIFFERENT WAYS OF DOING THEM, I
CANNOT POSSIBLY INCLUDE THEM HEREIN.**

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